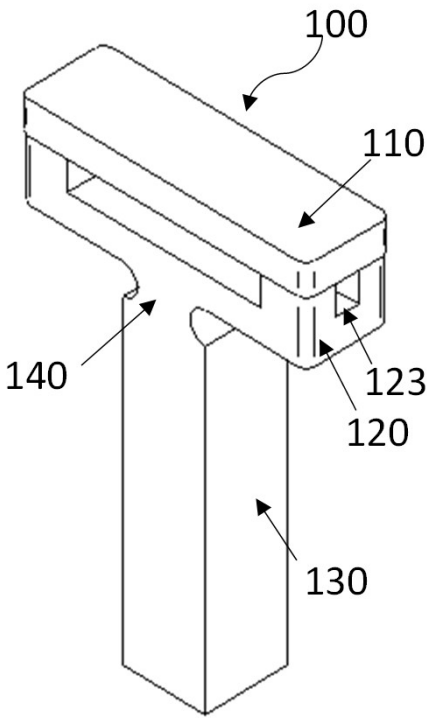


FIG. 1A

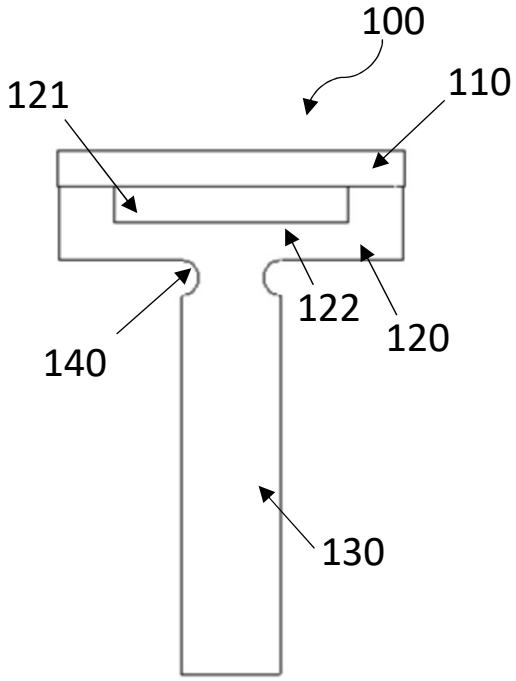


FIG. 1B

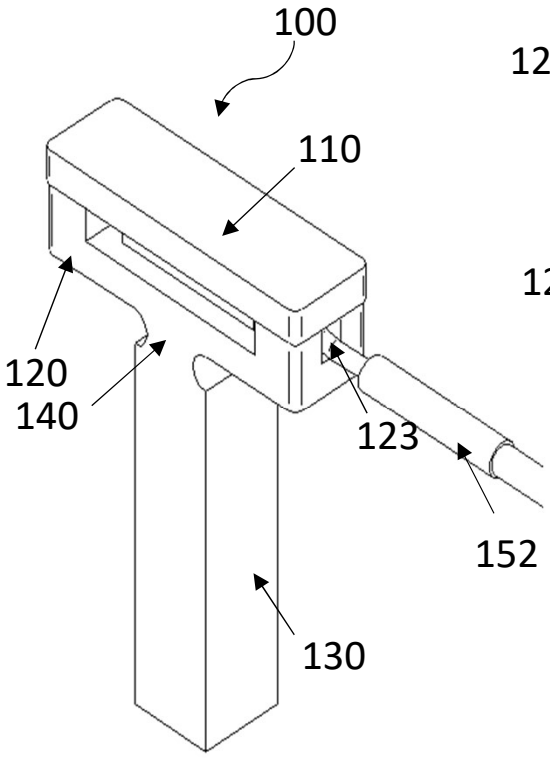


FIG. 1C

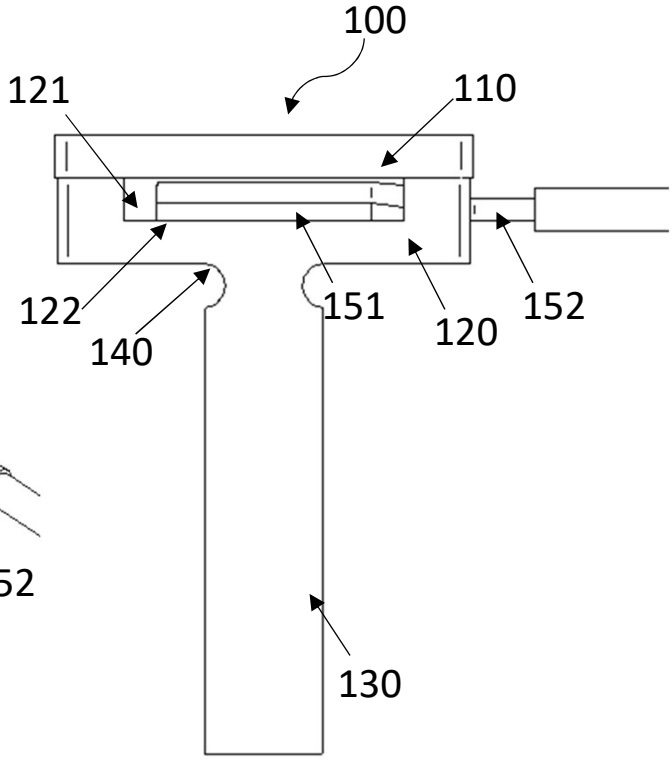


FIG. 1D

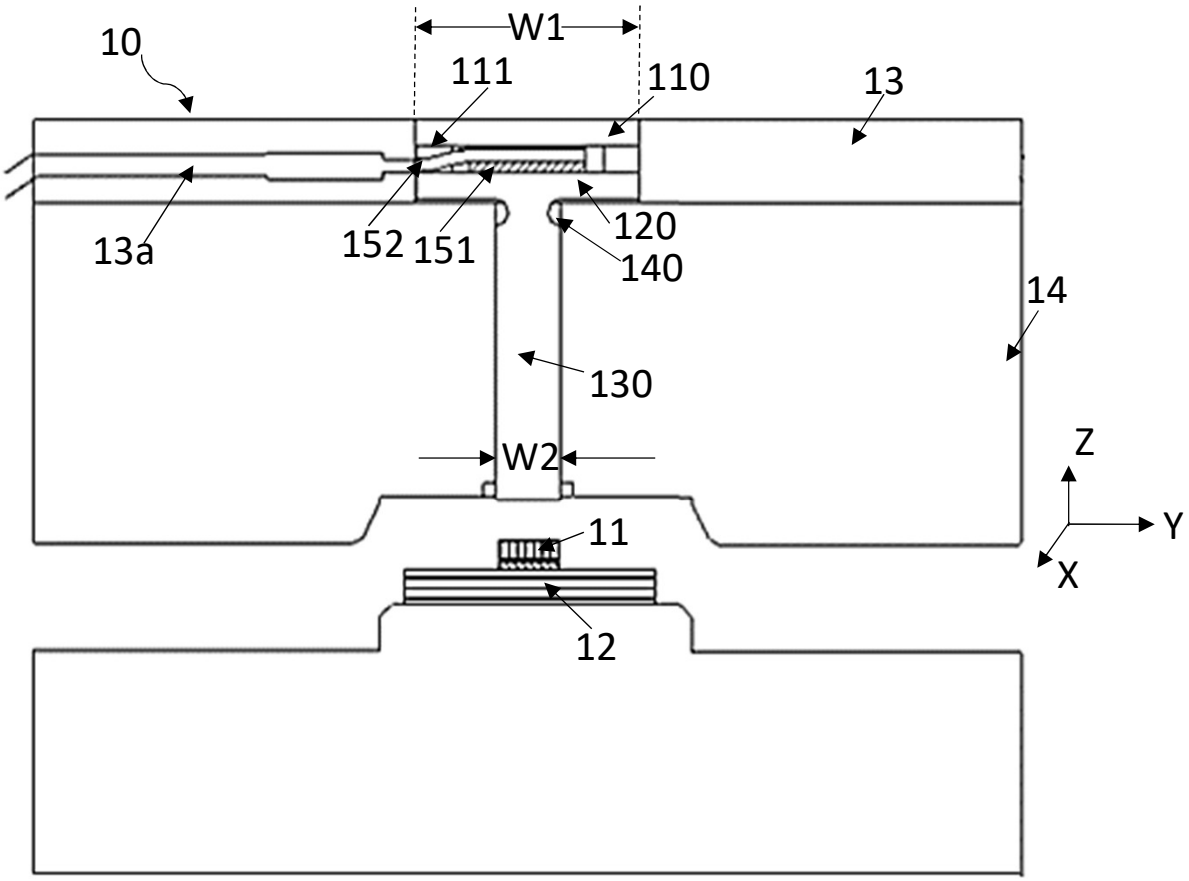


FIG. 2

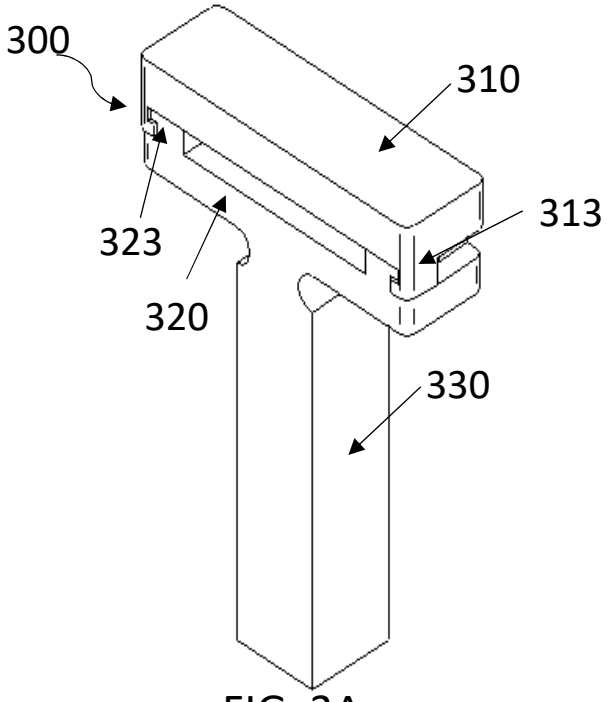


FIG. 3A

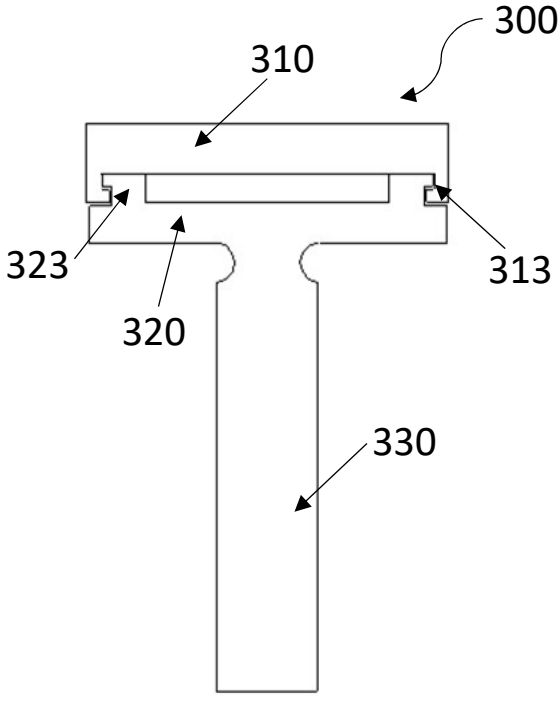


FIG. 3B

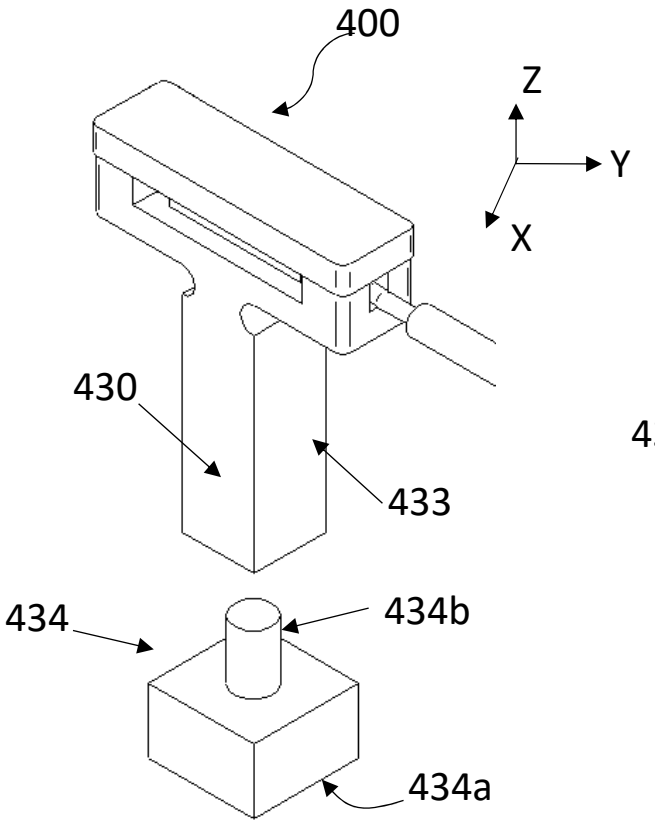


FIG. 4A

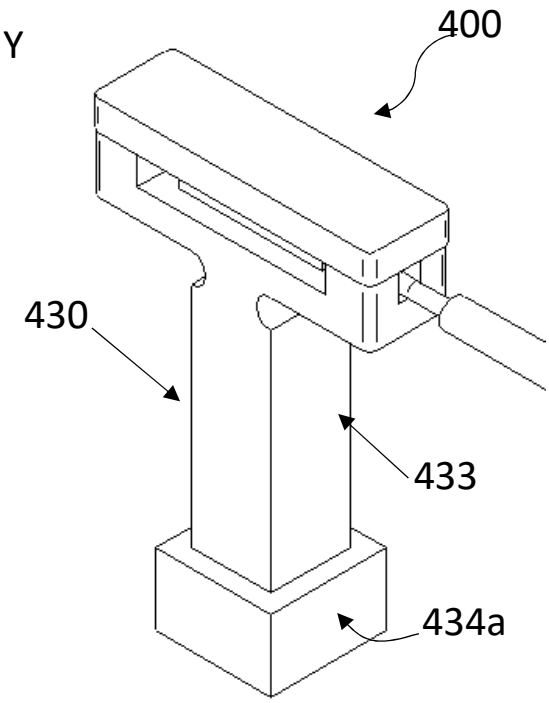


FIG. 4B

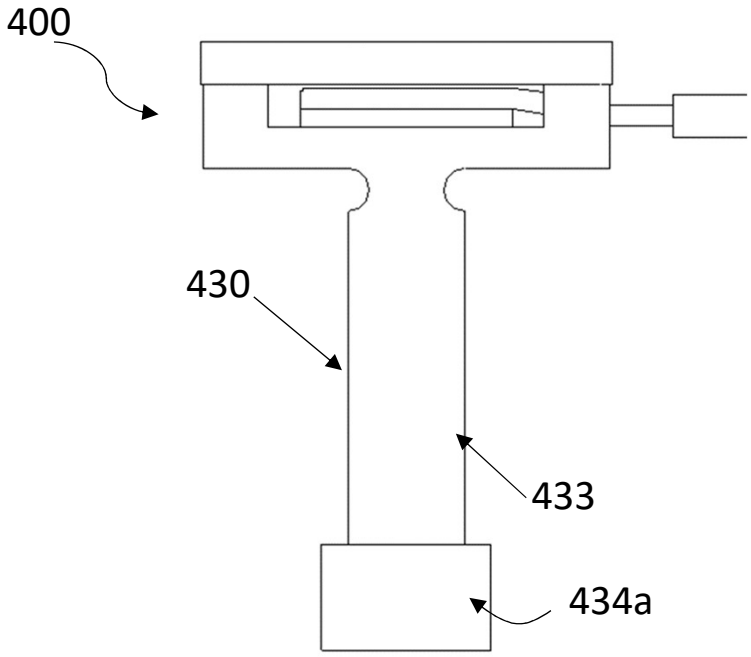


FIG. 4C

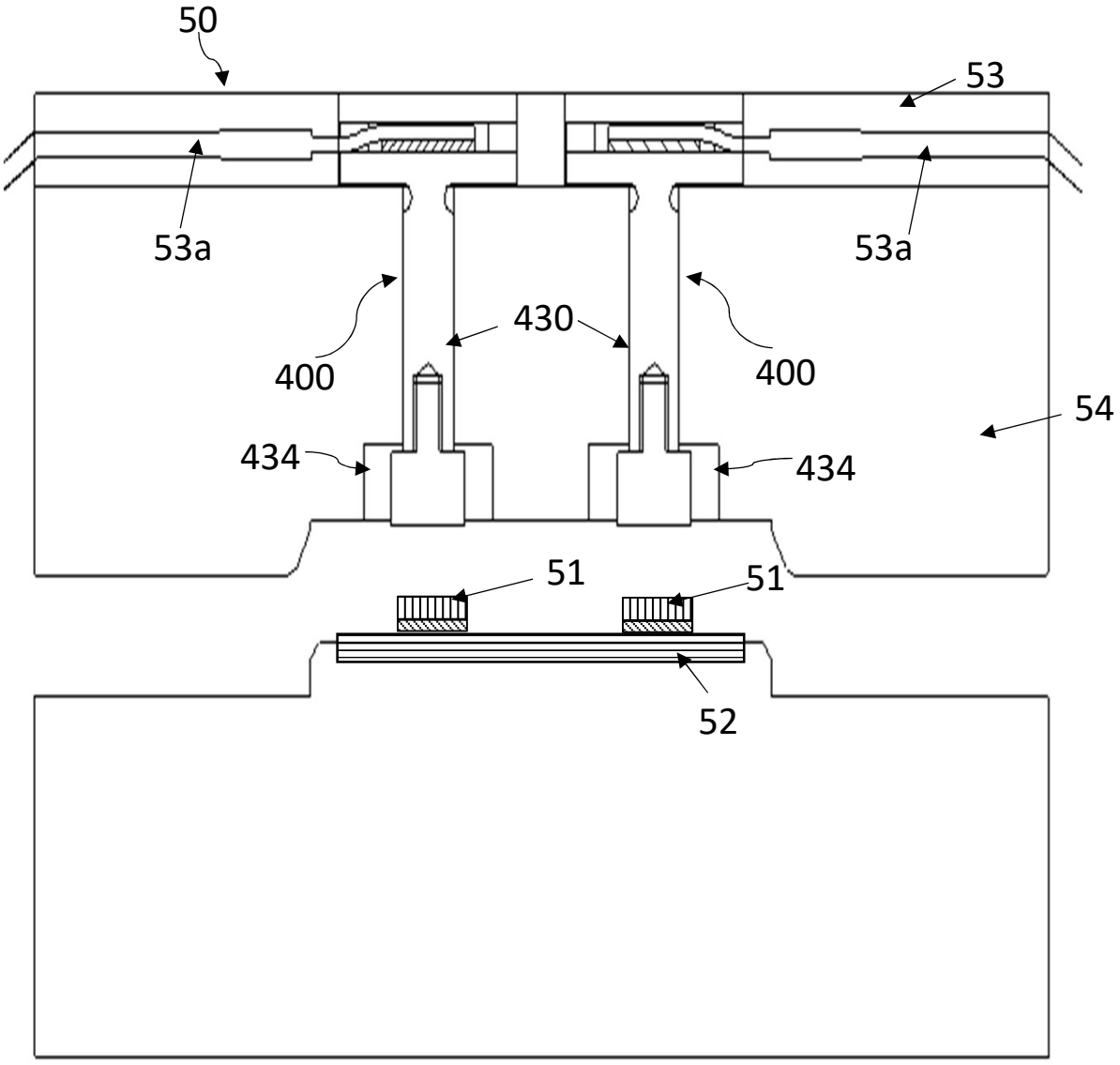


FIG. 5

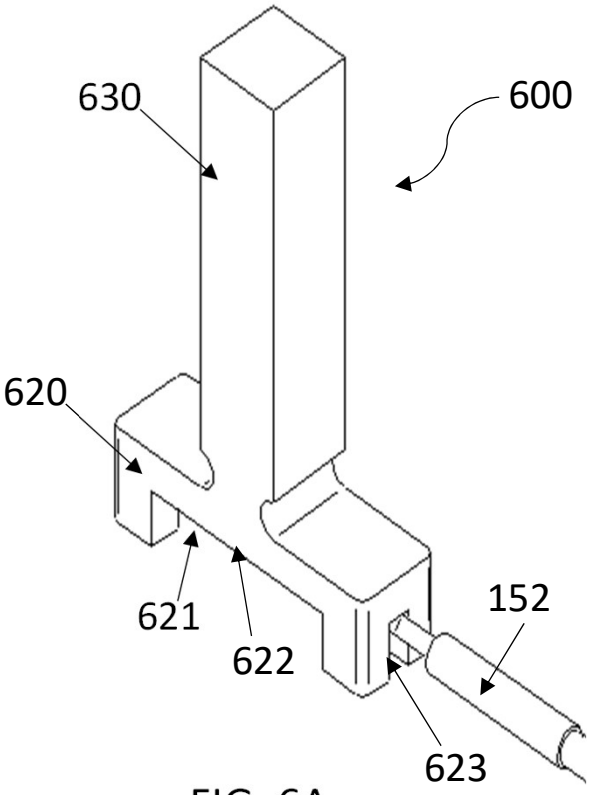


FIG. 6A

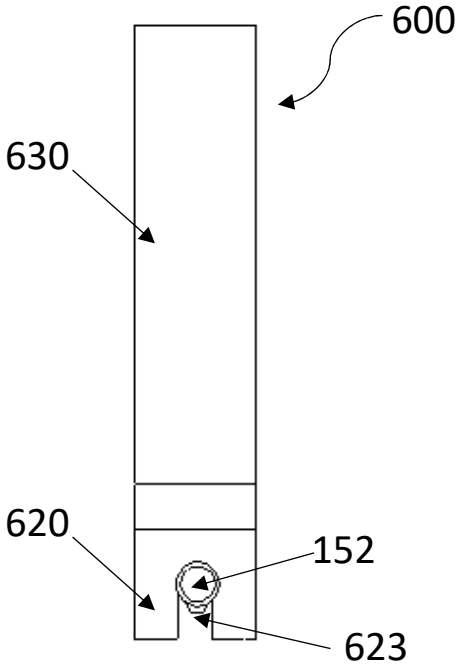


FIG. 6B

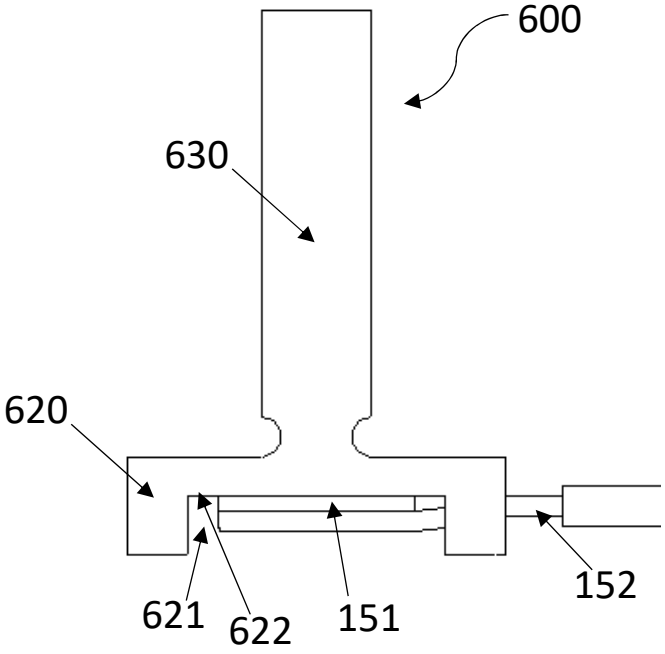


FIG. 6C

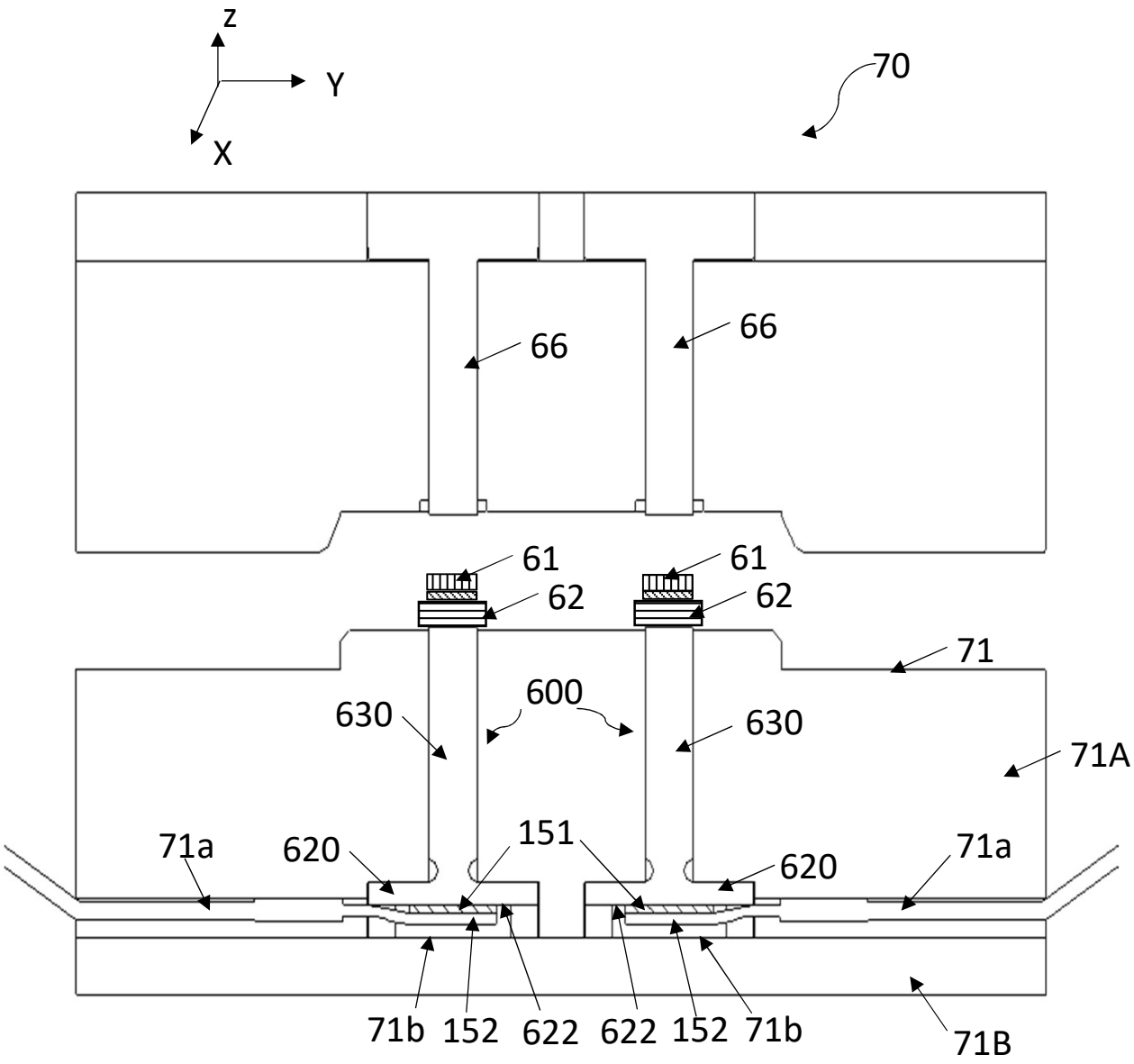

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71b
71B

FIG. 7

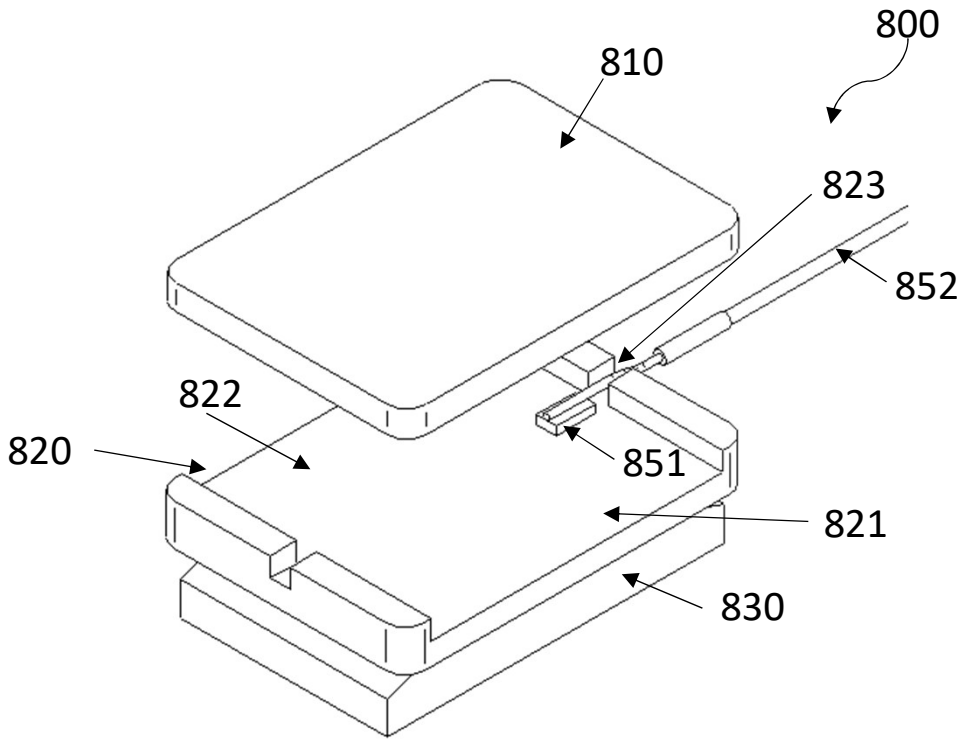

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FIG. 8A

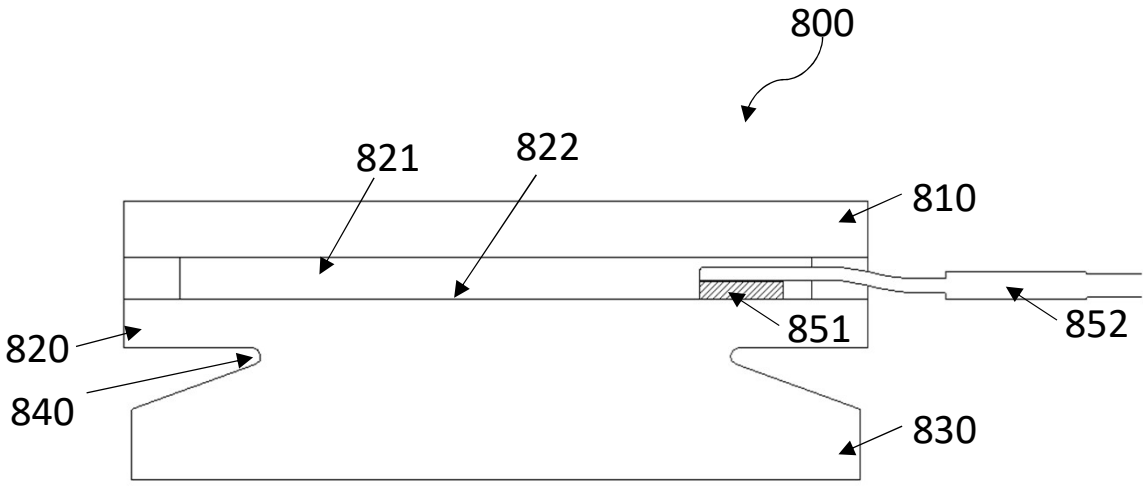

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FIG. 8B

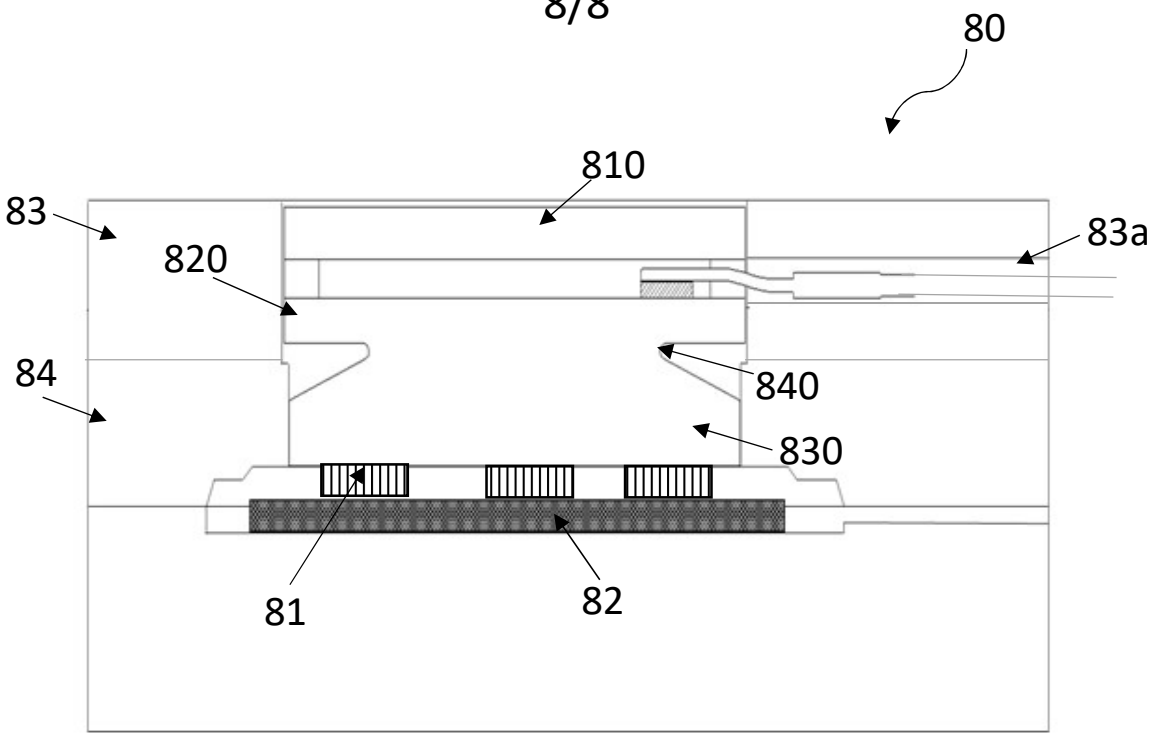

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83a
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830
81
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FIG. 8C

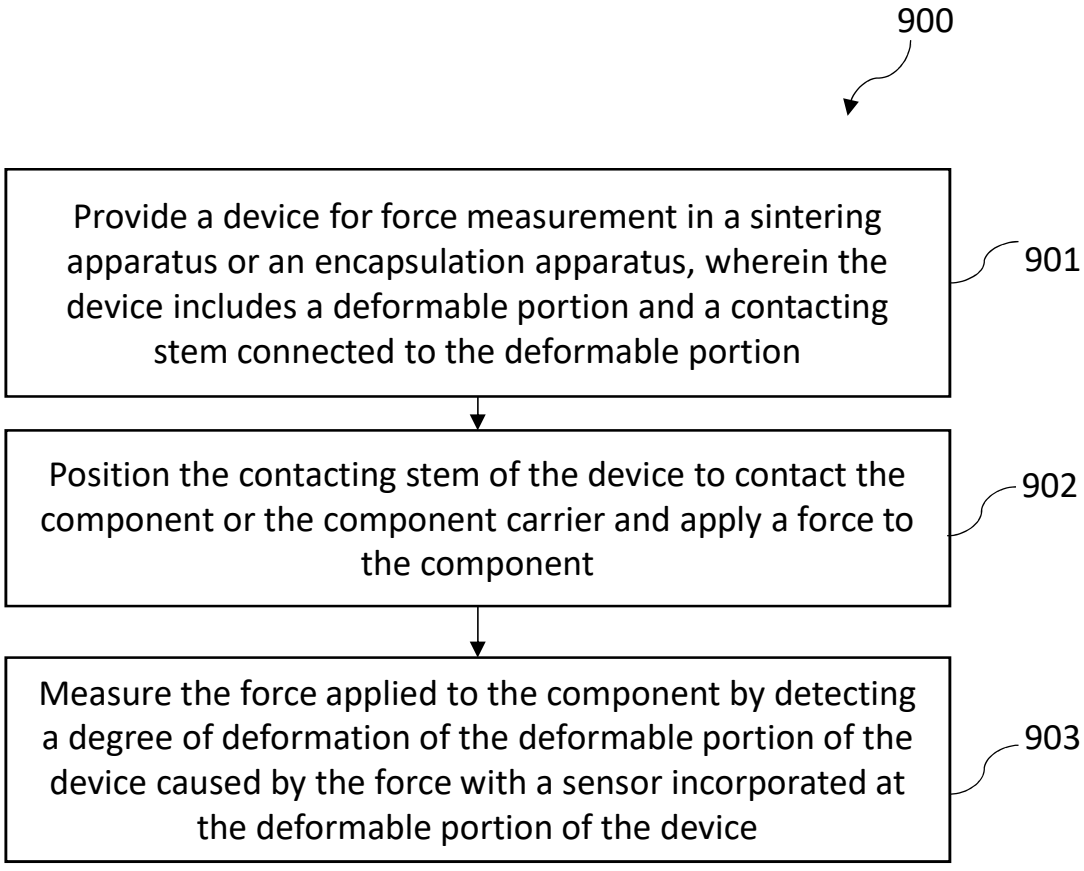

900
Provide a device for force measurement in a sintering apparatus or an encapsulation apparatus, wherein the device includes a deformable portion and a contacting stem connected to the deformable portion
901
Position the contacting stem of the device to contact the component or the component carrier and apply a force to the component
902
Measure the force applied to the component by detecting a degree of deformation of the deformable portion of the device caused by the force with a sensor incorporated at the deformable portion of the device
903

FIG. 9